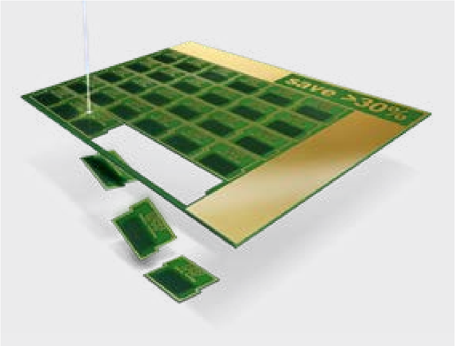
Setting New Standards with the Next Generation
Depaneling with LPKF CuttingMaster 2000

- Outstanding performance
- Optimal cost efficiency
- Integrated Tensor Technology



LPKF
Laser & Electronics

Performance, Efficiency, and Disruptive Technology: Maximum Return with the New CuttingMaster 2000 Generation

The new, specially developed laser sources and a patented beam deflection technology are unparalleled in the world and deliver performance that surpasses even the previous proven systems in the CuttingMaster 2000 platform. This gives users a clear competitive advantage.

Higher Performance at the Same Price

Thanks to the higher power, a performance increase of up to 25 % over that of the predecessor systems can be achieved – with the same investment. The cost-effectiveness makes the system highly interesting for an even wider range of applications, especially for machining of thick substrates.

Further Optimized Cost Efficiency

The optimal price-to-performance ratio has been supplemented by the system's greatly reduced operating costs. LPKF was able to increase the expected lifetime of the laser source by 25 % to up to 30 000 hours. Optimization of the maintenance concept resulted in elimination of the need for interim diode replacement and thus a further reduction in costs over the life cycle.

Game Changer: Tensor Technology

Tensor is a patented ultrafast beam deflection technology. Especially in conjunction with LPKF CleanCut for technically clean cutting of printed circuit boards, the technology enables cycle times to be reduced by up to 70 %.

Conclusion

The combination of the new green laser source with the unprecedented Tensor technology in the new system sets new standards in terms of performance, technical cleanliness, and efficiency of depaneling.

For users who are initially looking for a particularly cost-effective entry-level model with outstanding performance, the LPKF CuttingMaster 2122 is the system of choice.

LPKF CuttingMaster	2000 P (manual)	2000 Ci (automatic)
Max. working range (X x Y)	350 mm x 350 mm	350 mm x 250 mm
Positioning accuracy	± 25 µm	
Diameter of focused laser beam	~ 20 µm	
System dimensions (W x H x D)	875 mm x 1510 mm x 1125 mm*	
Weight	~ 450 kg	
Optional features	Universal fixture solutions, MES connection, optimized extraction, Uninterrupted Power Supply (UPS)	

* Height incl. status light: 2070 mm

Photos may also show optional accessories.

New system variants	CuttingMaster 2122	CuttingMaster 2240
Laser output	22 W	40 W
Wavelength	355 nm (UV)	532 nm (GR)
Pulse width	Nanosecond	Nanosecond
CleanCut Technology	•	•
Tensor Technology	–	•

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